

Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	3	ZHANG-BEICHAO.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/17 21:05
S2	4	LIU-WUPING.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/17 21:05
S3	37	HSIA-LIANG-CHOO.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/17 21:05
S4	34886	copper and interconnect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 22:17
S5	5773	copper and interconnect and cmp	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 22:29
S6	2681	copper and interconnect and cmp and damascene and barrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 22:32
S7	1099	copper and interconnect and cmp and damascene and barrier and etch adj stop	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 22:40
S8	960	copper and interconnect and cmp and dual adj damascene and barrier and etch adj stop	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 22:41
S9	87	copper and interconnect and cmp and dual adj damascene and barrier and etch adj stop and argon with sputter\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 22:42

S10	52	copper and interconnect and cmp and dual adj damascene and barrier and etch adj stop and argon with sputter\$3 and polymer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/17 21:06
S11	1	copper and interconnect and cmp and dual adj damascene and barrier and etch adj stop and argon with sputter\$3 and polymer and lift-off	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 22:52
S12	10	copper and interconnect and cmp and dual adj damascene and barrier and etch adj stop and polymer and lift-off	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/17 21:06
S13	1348	(438/687).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 21:06
S14	1010	(438/618).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 21:06
S15	792	(438/627).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 21:06
S16	731	(438/629).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 21:06
S17	976	(438/653).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 21:06
S18	2	("5,689,140").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/13 09:32
S19	2	("5,689,140").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/13 09:54

S20	2	("6,202,191").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/13 09:54
S21	2	("6,180,516").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/13 09:33
S22	13	copper and interconnect and cmp and dual adj damascene and barrier and etch adj stop and polymer and lift adj off	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/17 21:07
S23	20	copper and interconnect and cmp and dual adj damascene and barrier and etch adj stop and lift adj off	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/13 09:46
S25	97	copper and dual adj damascene and lift adj off	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/13 09:46
S26	3	copper and dual adj damascene and polymer near lift adj off	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/17 21:07
S27	7	copper and dual adj damascene and polymer with lift adj off	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/17 21:07
S28	75	copper and polymer with lift adj off	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/13 09:59
S29	7	copper and polymer with lift adj off same known	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/17 21:06
S30	5	ZHANG-BEICHAO.in	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/17 21:05

S31	8	LIU-WUPING .in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/17 21:05
S32	46	HSTA-LIANG-CHOO .in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/17 21:05
S33	61	copper and interconnect and cmp and dual adj damascene and barrier and etch adj stop and argon with sputter\$3 and polymer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/17 21:06
S34	33	copper and interconnect and cmp and dual adj damascene and barrier and etch adj stop and polymer and lift-off	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/17 21:06
S35	1063	(438/653).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 21:06
S36	1566	(438/687).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 21:06
S37	1131	(438/618).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 21:06
S38	900	(438/627).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 21:06
S39	859	(438/629).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 21:06
S40	8	copper and polymer with lift adj off same known	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/17 21:06

S41	7	copper and dual adj damascene and polymer with lift adj off	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/17 21:07
S42	3	copper and dual adj damascene and polymer near lift adj off	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/17 21:07
S43	35	copper and interconnect and cmp and dual adj damascene and barrier and etch adj stop and polymer and lift adj off	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/17 21:07